Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp		
S1	221	257/666,667,672,673,675,787.ccls. and (semiconductor with (encapsul\$4 or mold\$3) and land and lead adj frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 12:59		
S2	0	"60594859".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 12:59		
S3	6	("5969426"   "6215179"   "6247229"   "6278177"   "6294830"   "6309909").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 13:41		
S4	8	("5285352"   "5355283"   "5371404"   "5394009"   "5450283"   "5461197"   "5554887"   "5619070").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 13:54		
S5	237	"257".clas. and ((plurality near3 (ball or sphere or bump) with seal\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 15:17		
S6	0	"9990083"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:35		
S7		("9990083").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF ·	2007/08/01 16:35		
S8	0	"9990083".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:35		

S9	0	"09990083".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:37
S10	0	(method adj2 apparatus adj2 leadframe adj based adj grid adj array adj ic adj packaging).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:38
S11		(method adj2 apparatus adj2 lead-frame adj based adj grid adj array adj ic adj packaging).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:51
S12	2	("20020168796").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:10
S13	2	"6670222".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:26
S14	0	("jp2004-71898").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:26
S15	0	("jp200471898").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:26

C16		in200471808	HC DCDUB	OB	ON	2007/00/01 17:27
S16	0	jp200471898.pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:27
S17	0	"200471898".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:27
S18		("2004-71898.pn.").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:27
S19	0	jp2004-71898.pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:29
S20		("20020168796").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 18:54
S21	2	"5969426".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:56
S22	0	"257".clas. and (heat adj sink) and (passive adj device) and (thickness with chip adj attach\$4 adj site)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:58

S23	0	"257".clas. and (thickness with chip adj attach\$4 adj site)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:58
S24	86	"257".clas. and (thickness with chip adj attach\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:00
S25	1	"257".clas. and (distance with semiconductor near3 (routing adj circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:02
S26	1	distance with semiconductor near3 (routing adj circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:03